

ULTRA-SMALL LOW-INPUT-VOLTAGE LOW r_{ON} LOAD SWITCH

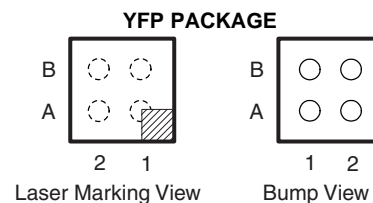
Check for Samples: [TPS22903](#), [TPS22904](#)

FEATURES

- **Input Voltage: 1.1 V to 3.6 V**
- **Ultra-Low ON-State Resistance**
 - $r_{ON} = 66\text{ m}\Omega$ at $V_{IN} = 3.6\text{ V}$
 - $r_{ON} = 75\text{ m}\Omega$ at $V_{IN} = 2.5\text{ V}$
 - $r_{ON} = 90\text{ m}\Omega$ at $V_{IN} = 1.8\text{ V}$
 - $r_{ON} = 135\text{ m}\Omega$ at $V_{IN} = 1.2\text{ V}$
- **500-mA Maximum Continuous Switch Current**
- **Quiescent Current $< 1\text{ }\mu\text{A}$**
- **Shutdown Current $< 1\text{ }\mu\text{A}$**
- **Low Control Input Threshold Enables Use of 1.2-V/1.8-V/2.5-V/3.3-V Logic**
- **Controlled Slew Rate (5 μs Max at 3.6 V)**
- **Quick Output Discharge (TPS22904 Only)**
- **ESD Performance Tested Per JESD 22**
 - **2000-V Human-Body Model (A114-B, Class II)**
 - **1000-V Charged-Device Model (C101)**
- **4-Terminal Wafer Chip-Scale Package (WCSP)**
 - **0.8 mm \times 0.8 mm, 0.4-mm Pitch, 0.5-mm Height**

APPLICATIONS

- PDAs
- Cell Phones
- GPS Devices
- MP3 Players
- Digital Cameras
- Peripheral Ports
- Portable Instrumentation



TERMINAL ASSIGNMENTS

B	GND	ON
A	V_{OUT}	V_{IN}
	2	1

DESCRIPTION

The TPS22903 and TPS22904 are ultra-small, low r_{ON} single channel load switches with controlled turn on. The device contains a P-channel MOSFET that can operate over an input voltage range of 1.1 V to 3.6 V. The switch is controlled by an on/off input (ON), which is capable of interfacing directly with low-voltage control signals. In TPS22904, a 85- Ω on-chip load resistor is added for output quick discharge when switch is turned off.

TPS22903 and TPS22904 are available in a space-saving 4-terminal WCSP 0.4-mm pitch (YFP). The devices are characterized for operation over the free-air temperature range of -40°C to 85°C .

FEATURE LIST

DEVICE	r_{ON} TYPICAL AT 3.6 V	SLEW RATE AT 3.6 V	QUICK OUTPUT DISCHARGE ⁽¹⁾	MAXIMUM OUTPUT CURRENT	ENABLE
TPS22903	66 m Ω	5 μs max	No	500 mA	Active high
TPS22904	66 m Ω	5 μs max	Yes	500 mA	Active high

(1) This feature discharges the output of the switch to ground through a 85- Ω resistor, preventing the output from floating.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

ORDERING INFORMATION⁽¹⁾

T _A	PACKAGE ⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING ⁽³⁾
–40°C to 85°C	WCSP – YFP (0.4-mm pitch)	Tape and reel	TPS22903YFPR	_ _ _ 4P _
			TPS22904YFPR	_ _ _ 4R _

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.
- (3) The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the wafer fab/assembly site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).

BLOCK DIAGRAM

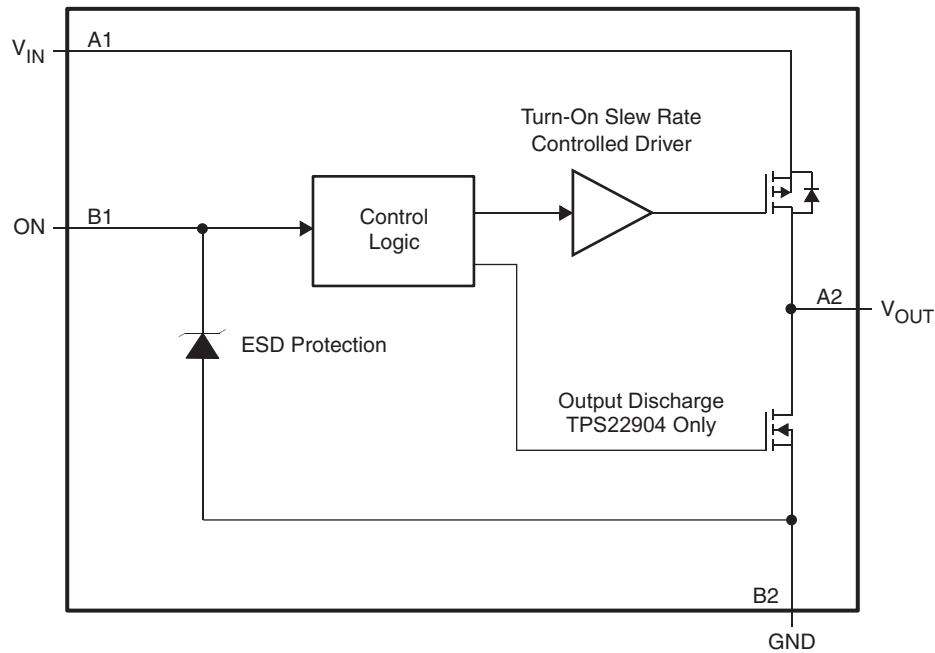


Figure 1. Functional Block Diagram

FUNCTION TABLE

ON (CONTROL INPUT)	V _{IN} TO V _{OUT}	V _{OUT} TO GND (TPS22904 ONLY)
L	OFF	ON
H	ON	OFF

TERMINAL FUNCTIONS

TERMINAL		I/O	DESCRIPTION
BALL NO.	NAME		
A1	V _{IN}	I	Input of the switch, bypass this input with a ceramic capacitor to ground
A2	V _{OUT}	O	Output of the switch
B1	ON	I	Switch control input, active high, do not leave floating
B2	GND	–	Ground

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

		MIN	MAX	UNIT
V _{IN}	Input voltage range	-0.3	4	V
V _{OUT}	Output voltage range		V _{IN} + 0.3	V
V _{ON}	Input voltage range	-0.3	4	V
P _D	Power dissipation at T _A = 25°C		0.48	W
I _{MAX}	Maximum continuous switch current		0.5	A
T _A	Operating free-air temperature range	-40	85	°C
T _{stg}	Storage temperature range	-65	150	°C
T _{lead}	Maximum lead temperature (10-s soldering time)		300	°C
ESD	Electrostatic discharge protection	Human-Body Model (HBM)		V
		Charged Device Model (CDM)		
			2000	
			1000	

- (1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

THERMAL IMPEDANCE RATINGS

		TYP	UNIT
θ _{JA}	Package thermal impedance ⁽¹⁾	205	°C/W
	YFP package		

- (1) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS

		MIN	MAX	UNIT
V _{IN}	Input voltage range	1.1	3.6	V
V _{OUT}	Output voltage range		V _{IN}	V
V _{IH}	High-level input voltage, ON	0.85	3.6	V
V _{IL}	Low-level input voltage, ON		0.4	V
C _{IN}	Input capacitor ⁽¹⁾	1		μF

- (1) See [Application Information](#)

ELECTRICAL CHARACTERISTICS

$V_{IN} = 1.1\text{ V to }3.6\text{ V}$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	T_A	MIN	TYP ⁽¹⁾	MAX	UNIT	
I_{IN}	Quiescent current	$I_{OUT} = 0$, $V_{IN} = V_{ON}$	Full			1	μA	
$I_{IN(OFF)}$	OFF-state supply current	$V_{ON} = \text{GND}$, $\text{OUT} = \text{Open}$	Full			1	μA	
$I_{IN(LEAKAGE)}$	OFF-state switch current	$V_{ON} = \text{GND}$, $V_{OUT} = 0$	Full			1	μA	
r_{ON}	ON-state resistance	$I_{OUT} = -200\text{ mA}$	25°C	Full	$V_{IN} = 3.6\text{ V}$	66	90	m Ω
					$V_{IN} = 2.5\text{ V}$	75	95	
			25°C	Full	$V_{IN} = 1.8\text{ V}$	90	115	
					$V_{IN} = 1.2\text{ V}$	135	175	
			25°C	Full	$V_{IN} = 1.1\text{ V}$	157	275	
						300		

r_{PD} Output pulldown resistance $V_{IN} = 3.3\text{ V}$, $V_{ON} = 0$ (TPS22904 only), $I_{OUT} = 30\text{ mA}$

r_{PD}	Output pulldown resistance	$V_{IN} = 3.3\text{ V}$, $V_{ON} = 0$ (TPS22904 only), $I_{OUT} = 30\text{ mA}$			85	135	Ω
I_{ON}	ON-state input leakage current	$V_{ON} = 1.1\text{ V to }3.6\text{ V or GND}$	Full			1	μA

(1) Typical values are at $V_{IN} = 3.3\text{ V}$ and $T_A = 25^\circ\text{C}$.

SWITCHING CHARACTERISTICS

$V_{IN} = 3.6\text{ V}$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	TPS22903			TPS22904			UNIT
		MIN	TYP ⁽¹⁾	MAX	MIN	TYP ⁽¹⁾	MAX	
t_{ON}	Turn-ON time	$I_{OUT} = 100\text{ mA}$, $C_L = 0.1\text{ }\mu\text{F}$		0.9	1.5	0.9	1.5	μs
t_{OFF}	Turn-OFF time	$I_{OUT} = 100\text{ mA}$, $C_L = 0.1\text{ }\mu\text{F}$		5.8	8	5.3	7	μs
t_r	V_{OUT} rise time	$I_{OUT} = 100\text{ mA}$, $C_L = 0.1\text{ }\mu\text{F}$		0.80	5	0.8	5	μs
t_f	V_{OUT} fall time	$I_{OUT} = 100\text{ mA}$, $C_L = 0.1\text{ }\mu\text{F}$		8.3	10	5.8	7	μs

(1) Typical values are at $T_A = 25^\circ\text{C}$.

TYPICAL CHARACTERISTICS

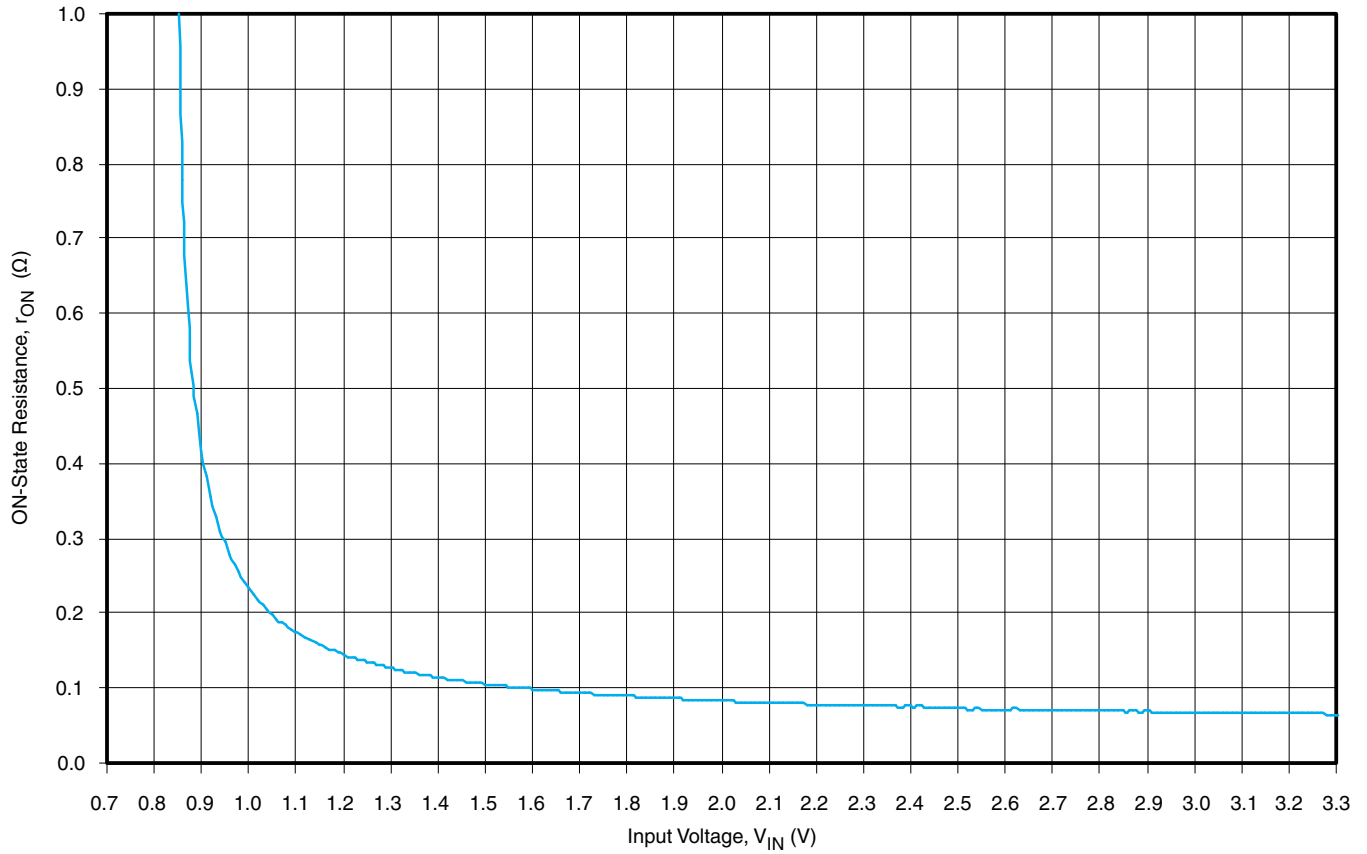


Figure 2. r_{ON} vs V_{IN}

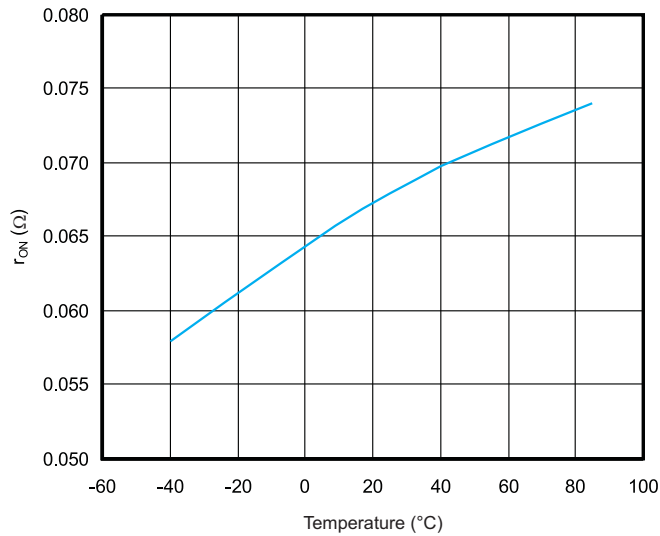


Figure 3. r_{ON} vs Temperature ($V_{IN} = 3.3$ V)

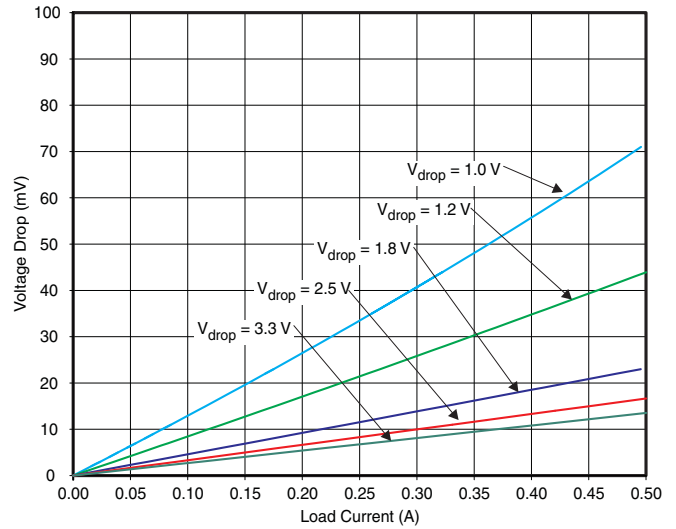


Figure 4. Voltage Drop vs Load Current

TYPICAL CHARACTERISTICS (continued)

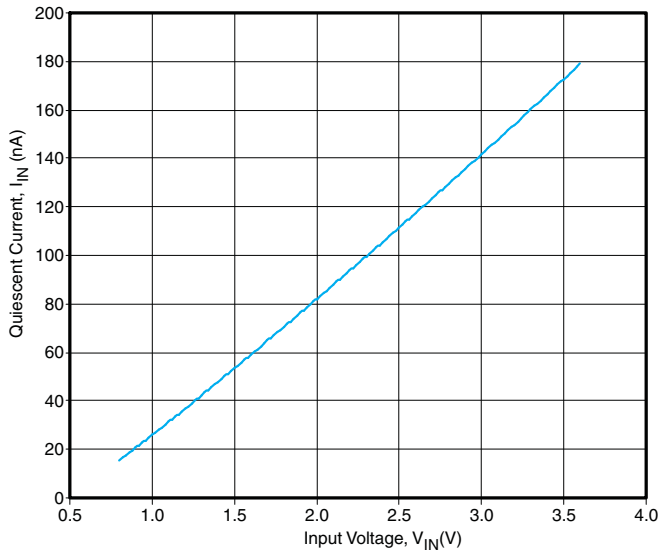


Figure 5. Quiescent Current vs V_{IN}
($V_{ON} = V_{IN}$, $I_{OUT} = 0$)

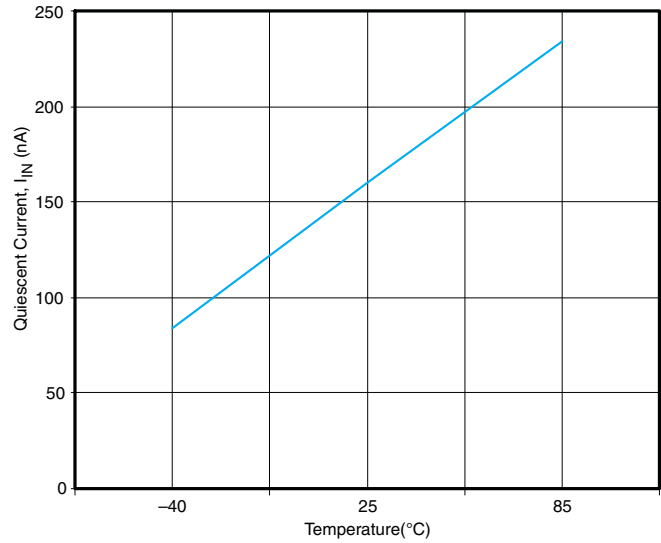


Figure 6. Quiescent Current vs Temperature
($V_{IN} = 3.3$ V, $I_{OUT} = 0$)

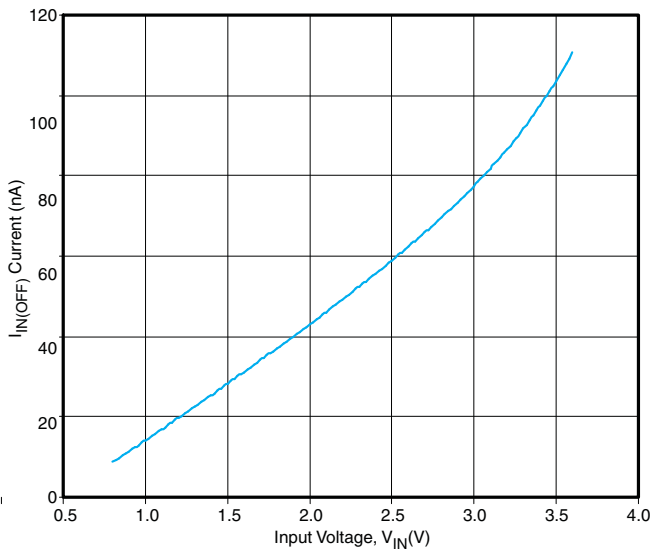


Figure 7. $I_{IN(OFF)}$ vs V_{IN} ($V_{ON} = 0$ V)

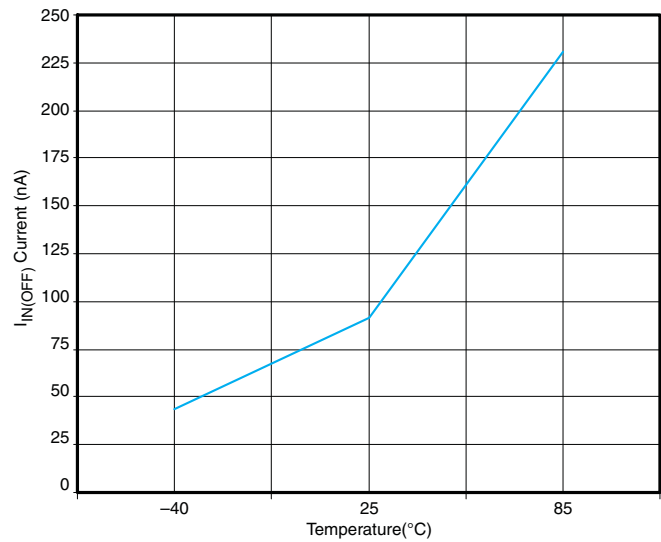


Figure 8. $I_{IN(OFF)}$ vs Temperature ($V_{IN} = 3.3$ V)

TYPICAL CHARACTERISTICS (continued)

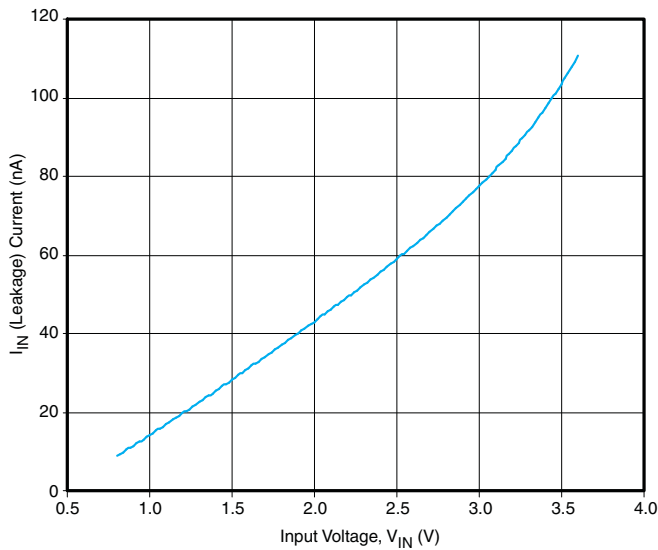


Figure 9. I_{IN} (Leakage) vs V_{IN} ($I_{OUT} = 0$)

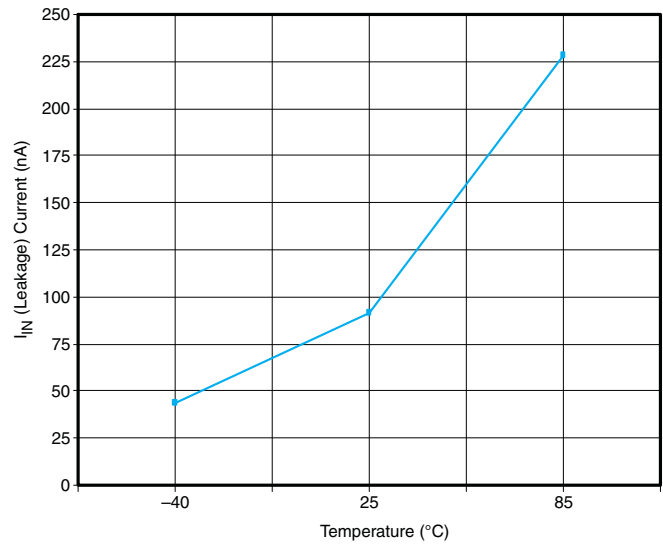


Figure 10. I_{IN} (Leakage) vs Temperature ($V_{IN} = 3.3$ V)

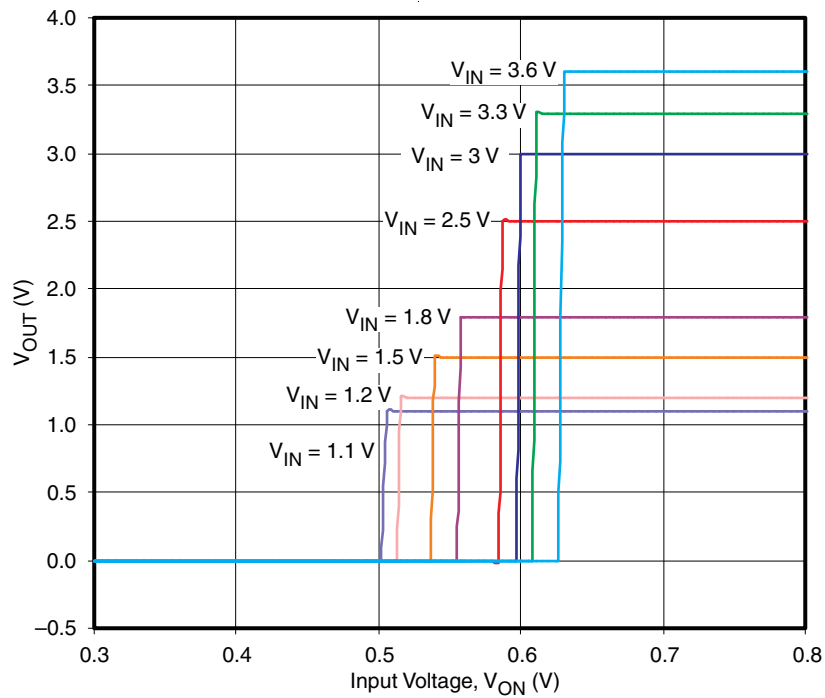


Figure 11. ON-Input Threshold

TYPICAL CHARACTERISTICS (continued)

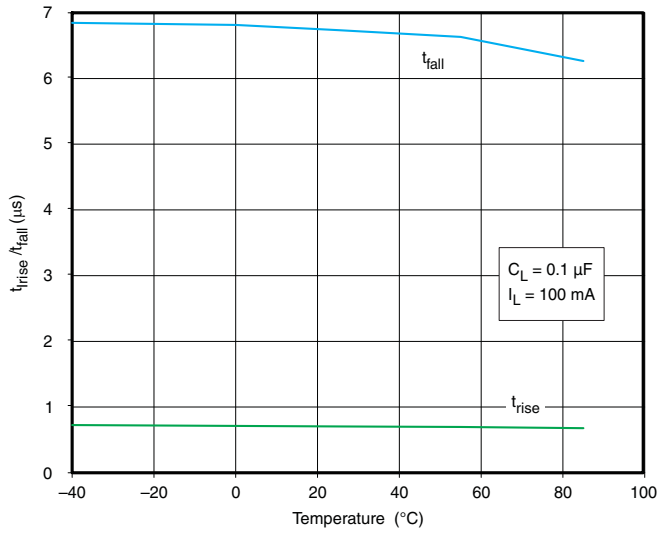


Figure 12. t_{rise} (TPS22903/4) / t_{fall} (TPS22903) vs Temperature ($V_{IN} = 3.3$ V)

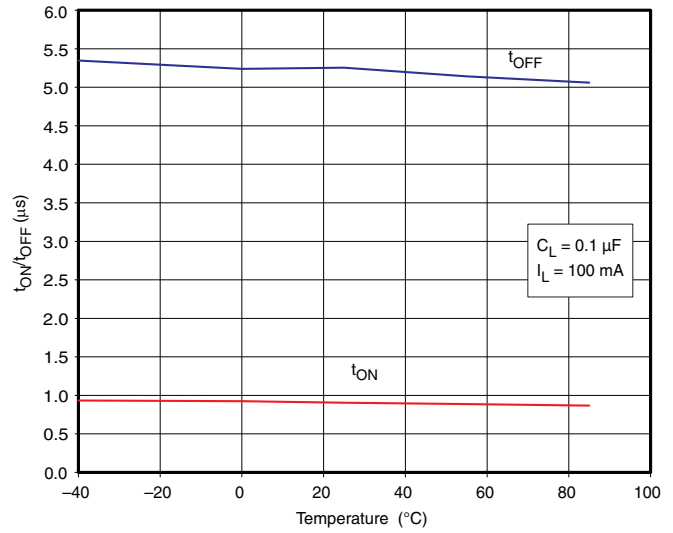


Figure 13. t_{ON} (TPS22903/4) / t_{OFF} (TPS22903) vs Temperature ($V_{IN} = 3.3$ V)

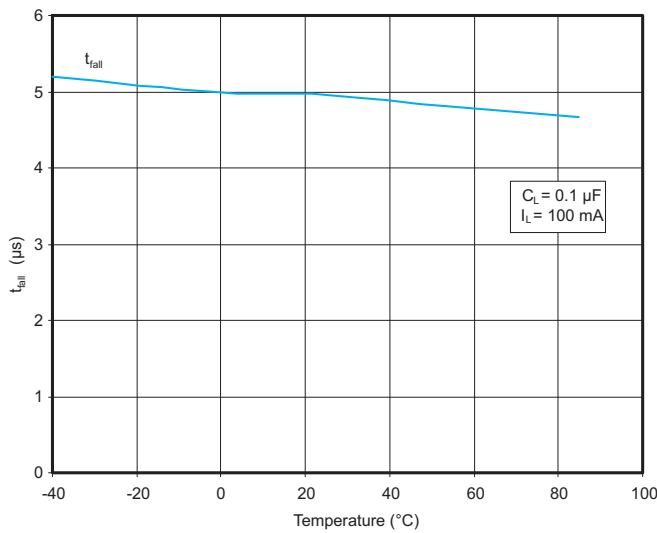


Figure 14. t_{fall} (TPS22904) vs Temperature ($V_{IN} = 3.3$ V)

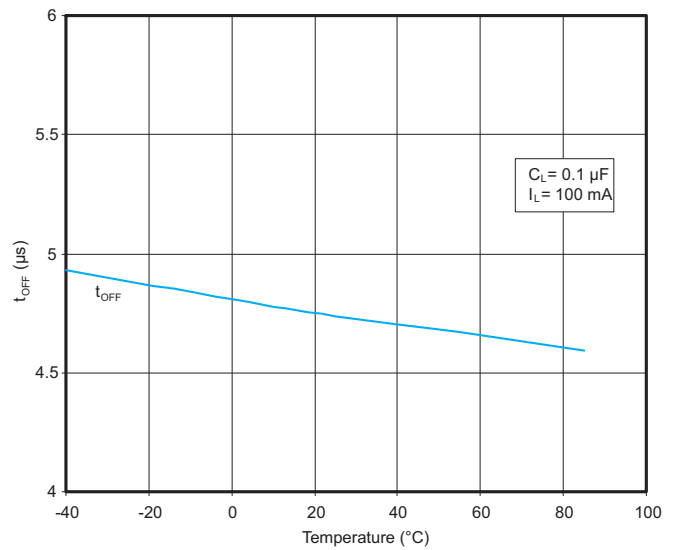


Figure 15. t_{OFF} (TPS22904) vs Temperature ($V_{IN} = 3.3$ V)

TYPICAL CHARACTERISTICS (continued)

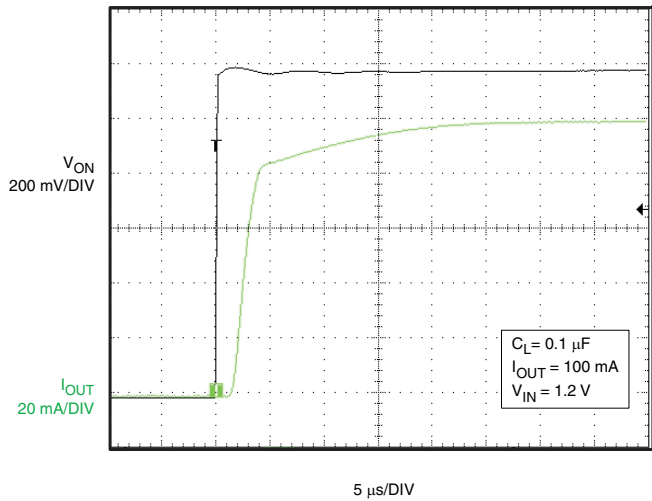


Figure 16. t_{ON} Response

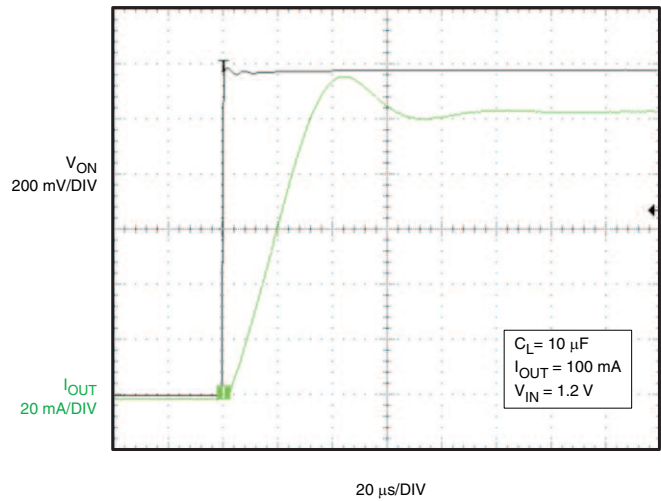


Figure 17. t_{ON} Response

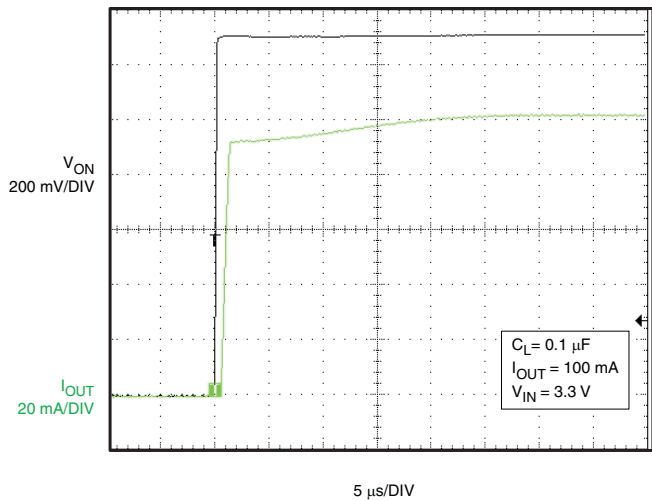


Figure 18. t_{ON} Response

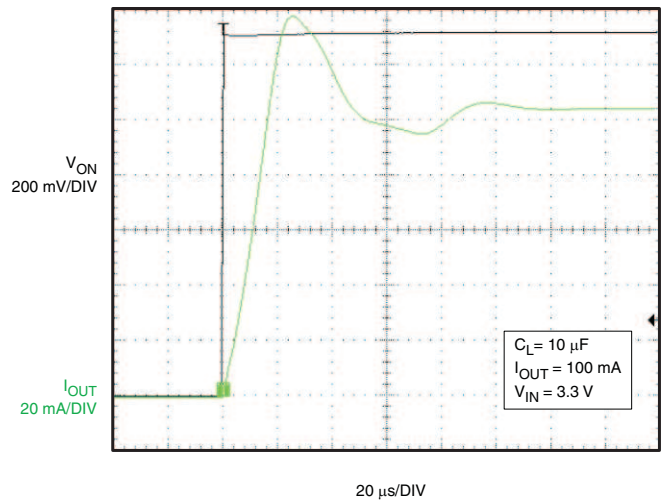


Figure 19. t_{ON} Response

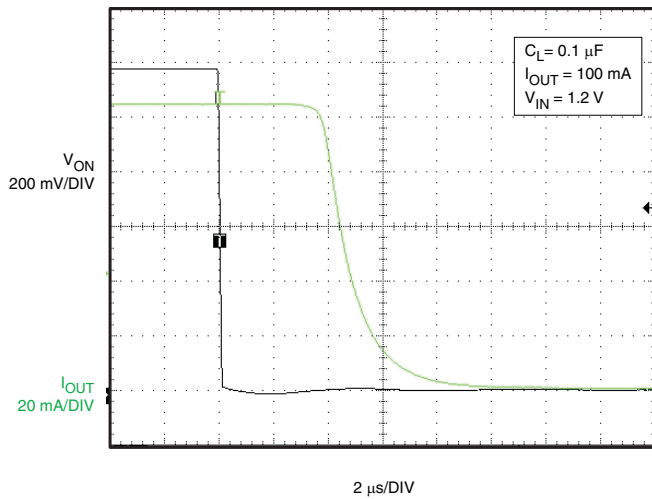


Figure 20. t_{OFF} Response (TPS22903)

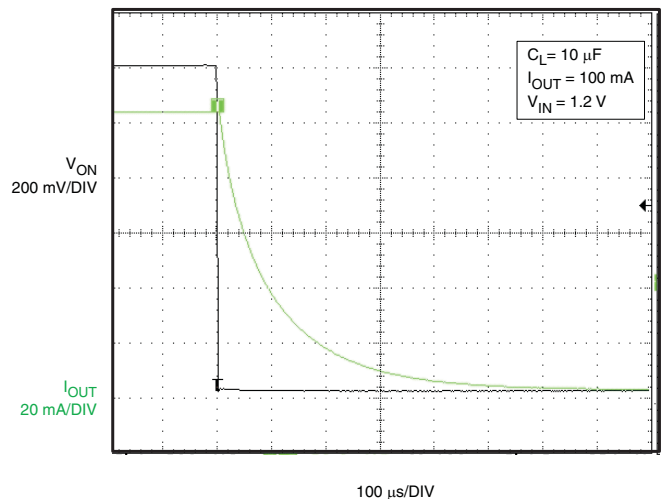


Figure 21. t_{OFF} Response (TPS22903)

TYPICAL CHARACTERISTICS (continued)

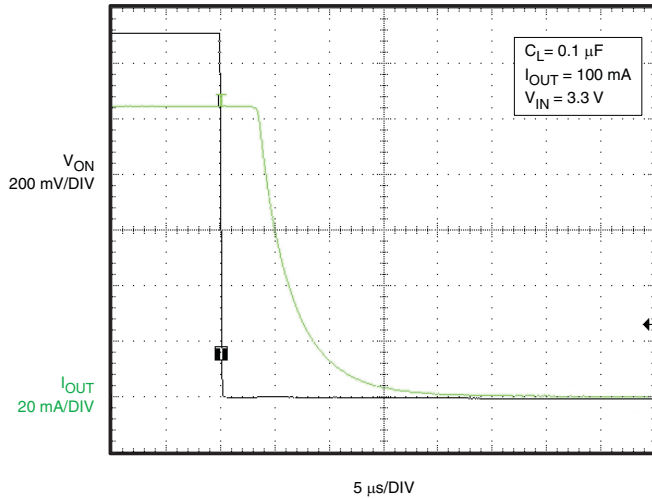


Figure 22. t_{OFF} Response (TPS22903)

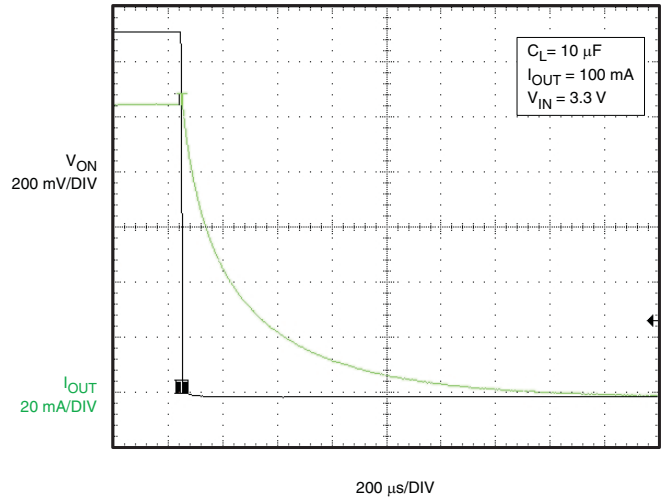


Figure 23. t_{OFF} Response (TPS22903)

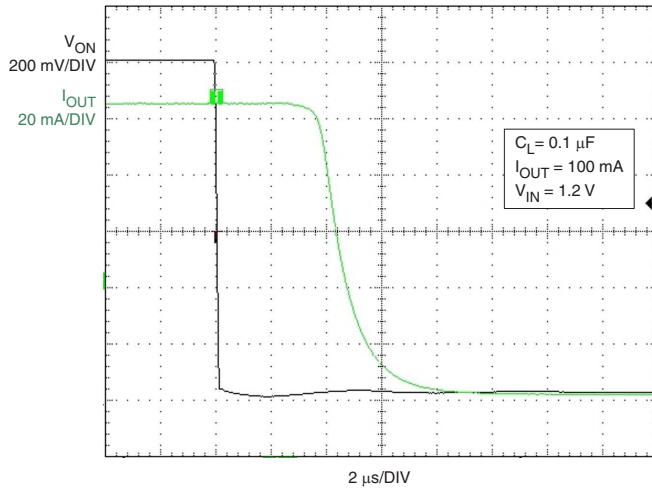


Figure 24. t_{OFF} Response (TPS22904)

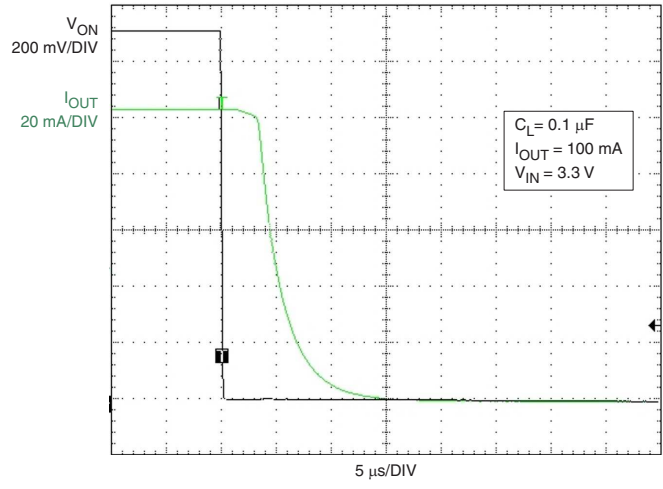


Figure 25. t_{OFF} Response (TPS22904)

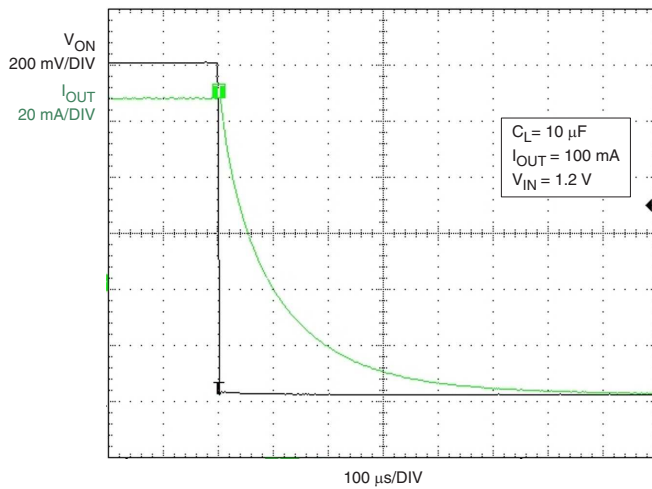


Figure 26. t_{OFF} Response (TPS22904)

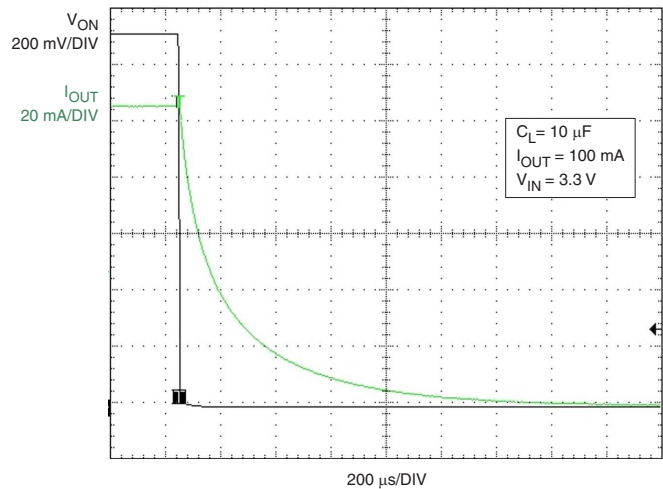
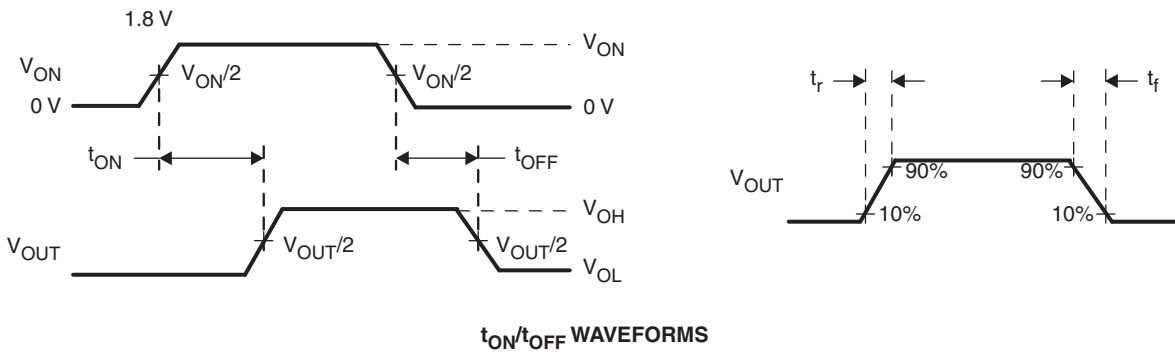
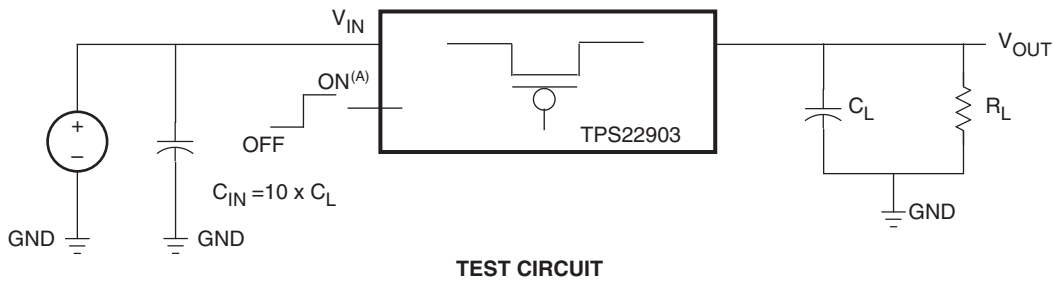


Figure 27. t_{OFF} Response (TPS22904)

PARAMETER MEASUREMENT INFORMATION



A. t_{rise} and t_{fall} of the control signal is 100 ns.

Figure 28. Test Circuit and t_{ON}/t_{OFF} Waveforms

APPLICATION INFORMATION

ON/OFF Control

The ON pin controls the state of the switch. Activating ON continuously holds the switch in the on state as there is no fault. ON is active-high and has a low threshold, making it capable of interfacing with low-voltage signals. The ON pin is compatible with standard GPIO logic thresholds. It can be used with any microcontroller with 1.2-V, 1.8-V, 2.5-V, or 3.3-V GPIOs.

Input Capacitor (Optional)

To limit the voltage drop on the input supply caused by transient in-rush currents when the switch turns on into a discharged load capacitor or short-circuit, a capacitor needs to be placed between V_{IN} and GND. A 1- μ F ceramic capacitor, C_{IN} , placed close to the pins, is usually sufficient. Higher values of C_{IN} can be used to further reduce the voltage drop during high-current application. When switching heavy loads, it is recommended to have an input capacitor about 10 times higher than the output capacitor to avoid excessive voltage drop.

Output Capacitor (Optional)

Due to the integral body diode in the PMOS switch, a C_{IN} greater than C_L is highly recommended. A C_L greater than C_{IN} can cause V_{OUT} to exceed V_{IN} when the system supply is removed. This could result in current flow through the body diode from V_{OUT} to V_{IN} .

Board Layout

For best performance, all traces should be as short as possible. To be most effective, the input and output capacitors should be placed close to the device to minimize the effects that parasitic trace inductances may have on normal and short-circuit operation. Using wide traces for V_{IN} , V_{OUT} , and GND helps minimize the parasitic electrical effects along with minimizing the case-to-ambient thermal impedance.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS22903YFPR	ACTIVE	DSBGA	YFP	4	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	4P (2 ~ N)	Samples
TPS22904YFPR	ACTIVE	DSBGA	YFP	4	3000	Green (RoHS & no Sb/Br)	Call TI SNAGCU	Level-1-260C-UNLIM	-40 to 85	4R (2 ~ N)	Samples
TPS22904YFPT	ACTIVE	DSBGA	YFP	4	250	Green (RoHS & no Sb/Br)	Call TI	Level-1-260C-UNLIM	-40 to 85	4R 2	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and

continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS22903YFPR	DSBGA	YFP	4	3000	180.0	8.4	0.89	0.89	0.58	4.0	8.0	Q1
TPS22904YFPR	DSBGA	YFP	4	3000	180.0	8.4	0.89	0.89	0.58	4.0	8.0	Q1
TPS22904YFPT	DSBGA	YFP	4	250	180.0	8.4	0.89	0.89	0.58	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS

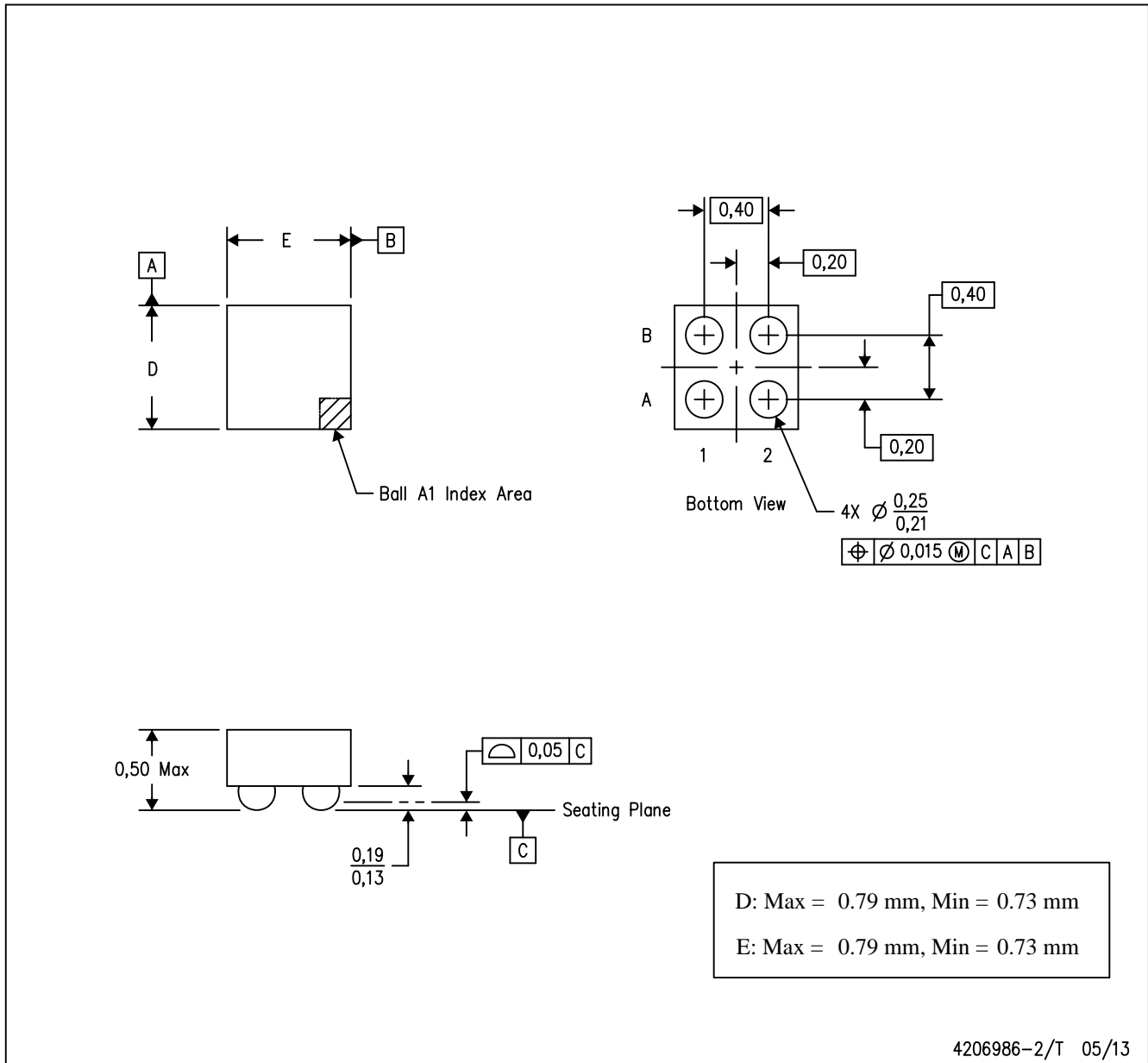

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS22903YFPR	DSBGA	YFP	4	3000	220.0	220.0	34.0
TPS22904YFPR	DSBGA	YFP	4	3000	220.0	220.0	34.0
TPS22904YFPT	DSBGA	YFP	4	250	220.0	220.0	34.0

MECHANICAL DATA

YFP (S-XBGA-N4)

DIE-SIZE BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. NanoFree™ package configuration.

NanoFree is a trademark of Texas Instruments

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com